**DATE 10 OCT 2011** 



## UDFN10 3x3, 0.5P (Leads 2 & 3 Tied) CASE 517CC **ISSUE O** АВ **EXPOSED Cu** MOLD CMPD **DETAIL B** ALTERNATE CONSTRUCTION PIN ONE REFERENCE С (0.17)0.15 - L1 △ 0.15 C **TOP VIEW** DETAIL B **DETAIL A** С 0.10 ALTERNATE TERMINAL CONSTRUCTIONS △ 0.08 C C SEATING PLANE NOTE 4 **SIDE VIEW** D2 DETAIL A **E2** 10X **b** 0.10 C A $\oplus$ 0.05 C NOTE 3 **BOTTOM VIEW** RECOMMENDED **SOLDERING FOOTPRINT\*** 0.50 10X 0.62 **PITCH**

1.81 3.30

0.30

**DIMENSIONS: MILLIMETERS** 

## NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. DIMENSION & APPLIES TO PLATED
- TERMINAL AND IS MEASURED BETWEEN
  0.15 AND 0.30mm FROM THE TERMINAL TIP.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.45	0.55	
A1	0.00	0.05	
A3	0.13 REF		
b	0.15	0.25	
D	3.00 BSC		
D2	2.39	2.59	
E	3.00 BSC		
E2	1.59	1.79	
е	0.50 BSC		
L	0.35	0.45	
L1		0.15	

## **GENERIC MARKING DIAGRAM\***



= Assembly Location Α

L = Wafer Lot

Υ = Year

W = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	UDFN10 3X3, 0.5P (LEADS 2 & 3 TIED)		PAGE 1 OF 1

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0.80

PACKAGE OUTLINE